

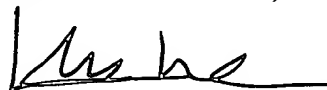
24. An electronic device comprising a semiconductor device and a circuit board to which said semiconductor device is electrically connected assembled using a thermosetting resin composition according to Claim 1 as an underfill sealant between the semiconductor device and the circuit board, wherein reaction products of the composition are capable of softening and losing their adhesiveness under exposure to temperature conditions in excess of those used to cure the composition.

Should the Examiner have any questions or concerns regarding any of this information, the Examiner is invited to contact the Applicants' undersigned representative by telephone at 412-471-8815.

Respectfully submitted,

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